# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP 242 G2 Notebook PC

---

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

---

PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver #1</td>
<td>Type-cross #1</td>
</tr>
<tr>
<td>Screwdriver #2</td>
<td>Type-slot</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Slide the battery latch to the unlock position and disassemble battery.
2. Disassemble left / right hinge caps and HDD cover (screw x1).
3. Dissemble HDD, remove HDD rubber and HDD cable.
4. Disconnect WLAN cables and disassemble WLAN card (screw x1).
5. Disassemble DDR cover (screw x1) and ODD (screw x1).
6. Disassemble DDR.
7. Loosen BTCB ODD rim screws (x2) and disconnect Fan cable.
8. Loosen BTCB HDD screws (x2) and disconnect LVDS cable.
9. Loosen BTCB screws (x12).
10. Disassemble KB FPC and KB.
11. Disconnect Finger printer FFC, Pick button/B FFC and Power button/B FFC.
12. Disassemble TPCB.
13. Remove FAN Mylar, speaker acid type and disconnect speaker cable.
14. Disassemble USB/B (screw x1).
15. Disassemble Fan (screw x2).
17. Disassemble M/B (screw x3).
18. Disassemble speaker cable and speakers.
19. Disassemble WLAN antennas.
20. Loosen LCM hinge screws (x6) and disassemble LVDS cable.
22. Disassemble BTCB.
24. Disassemble thermal module (UMA model: screw x4, DIS model: screw x6).
25. Disassemble CPU.
26. Take out M/B.
27. Remove Mylar (x2) and loosen bezel screws (x2).
29. Disassemble acid tape and LVDS cable from cable through.
30. Loosen LCD screws (x8).
31. Disassemble camera module.
32. Disassemble LCD.
33. Disassemble hinge bracket-R (screw x2).
34. Disassemble hinge bracket-L (screw x2).
35. Disassemble LVDS cable.
36. Disassemble antenna cable (MAIN).
37. Disassemble antenna cable (AUX)
38. Take out BTDL.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module
3.23 Remove service door
3.24 LCD module set disassembly
3.25 Top case disassembly
3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly